MALS068X

Silicon planar type

For constant voltage and surge absorption circuits

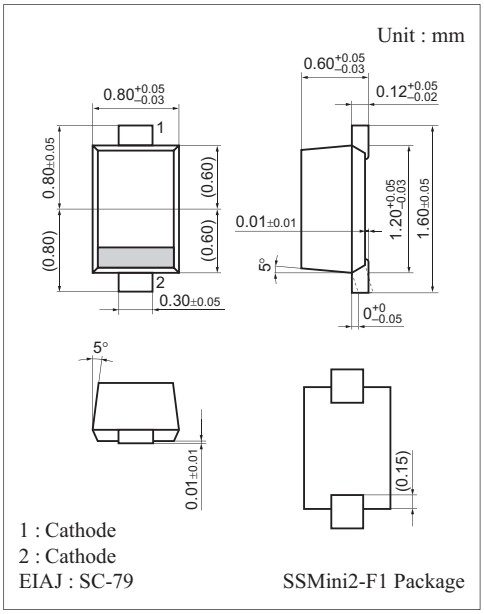
■ Features

- Bi-directional and high electrostatic discharge ESD
- Small terminal capacitance C_t

■ Absolute Maximum Ratings $T_a = 25°C$

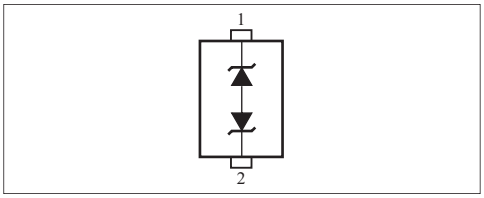
Parameter	Symbol	Rating	Unit
Repetitive peak forward current	I_{FRM}	200	mA
Total power dissipation *1	P_T	150	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–55 to +150	°C
Electrostatic discharge *2	ESD	±15	kV

Note) ∗1: P_T = 150 mW achieved with a printed circuit board.
∗2: Test method: IEC61000-4-2
(C = 150 pF, R = 330 Ω, Contact discharge: 10 times)



Marking Symbol: RX

Internal Connection



■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Zener voltage *	V_Z	I_Z = 5 mA	6.5	7.0	7.5	V
Zener operating resistance	R_Z	I_Z = 5 mA			20	Ω
Reverse current	I_R	V_R = 4.0 V			50	nA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz		15		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. The temperature must be controlled 25°C for V_Z mesurement.
V_Z value measured at other temperature must be adjusted to V_Z (25°C)
3. ∗: V_Z guaranted 20 ms after current flow.

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